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(54) Title: ADAPTIVE PATTERNING FOR PANELIZED PACKAGING

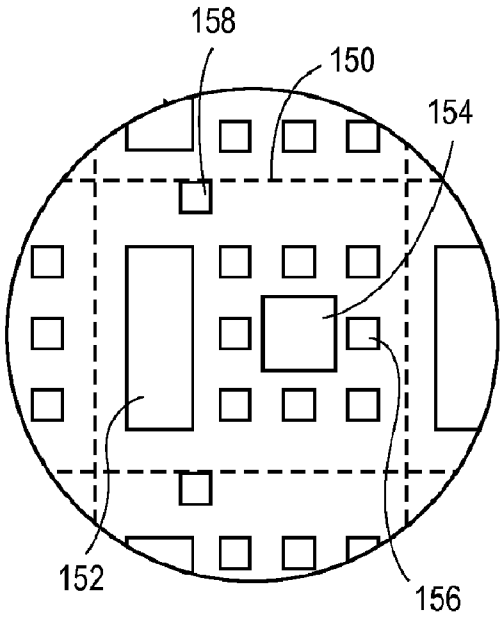


FIG. 1D

(57) Abstract: An adaptive patterning method and system for fabricating panel based package structures is described. Misalignment for individual device units in a panel or reticulated wafer may be adjusted for by measuring the position of each individual device unit and forming a unit-specific pattern over each of the respective device units.

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